

## Description

The HSS06P03 is the high cell density trenched P-Ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

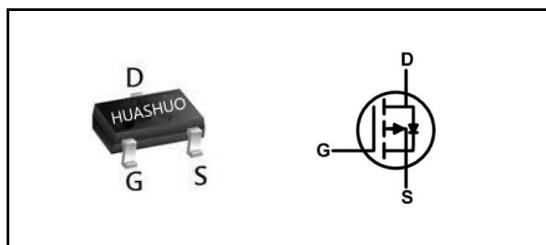
The HSS06P03 meet the RoHS and Green Product requirement, with full function reliability approved.

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

V <sub>DS</sub>	-30	V
R <sub>DSON,max</sub>	28	mΩ
I <sub>D</sub>	-6	A

## SOT23 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-6	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-24	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.25	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	100	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	80	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-30	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-4.2\text{A}$	---	23	28	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-4\text{A}$	---	30	36	
		$V_{\text{GS}}=-2.5\text{V}$ , $I_{\text{D}}=-1\text{A}$	---	38	48	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1	-1.5	-2	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	4	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-1\text{A}$	---	24.1	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	3.8	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	4.2	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $R_{\text{G}}=10\Omega$ , $R_{\text{L}}=15\Omega$ , $I_{\text{D}}=-1\text{A}$	---	48	---	$\text{ns}$
$T_r$	Rise Time		---	3.2	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	18	---	
$T_f$	Fall Time		---	9	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1181	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	143	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	102	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_{\text{G}}=V_{\text{D}}=0\text{V}$ , Force Current	---	---	-6	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.



**HUASHUO**  
SEMICONDUCTOR

**HSS06P03**

### Typical Characteristics

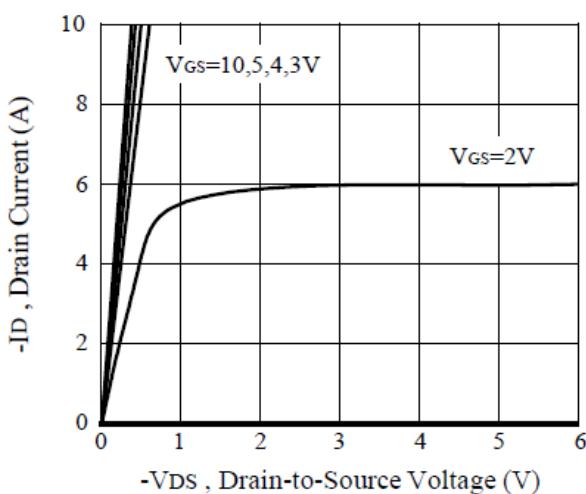


Figure 1. Output Characteristics

### P-Ch 30V Fast Switching MOSFETs

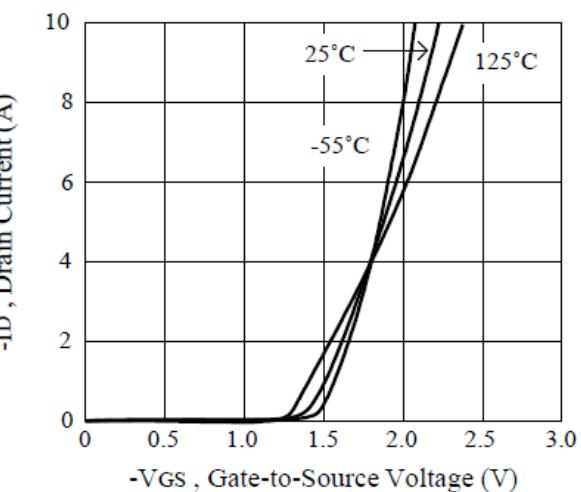


Figure 2. Transfer Characteristics

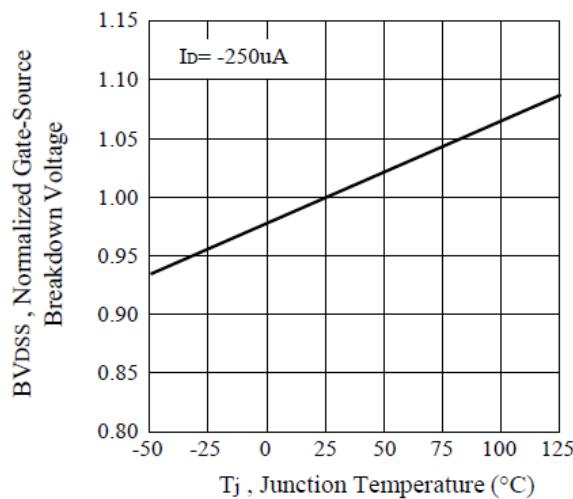


Figure 6. Breakdown Voltage Variation with Temperature

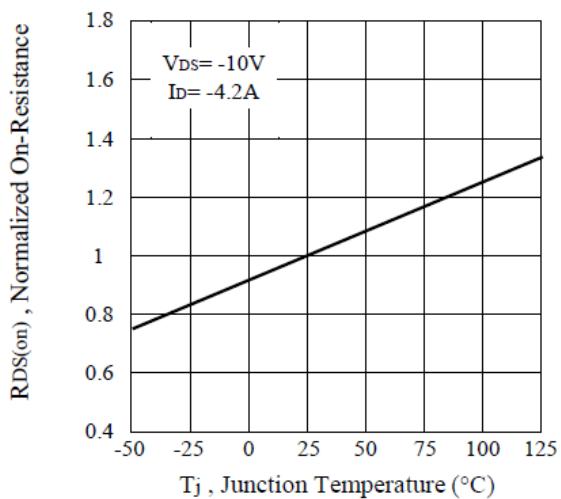


Figure 4. On-Resistance Variation with Temperature

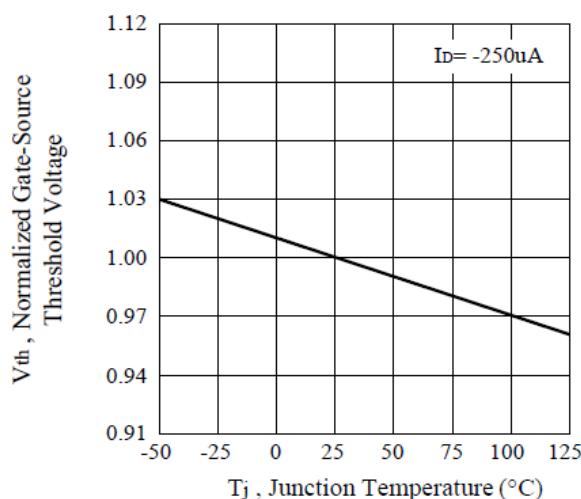


Figure 5. Gate Threshold Variation with Temperature

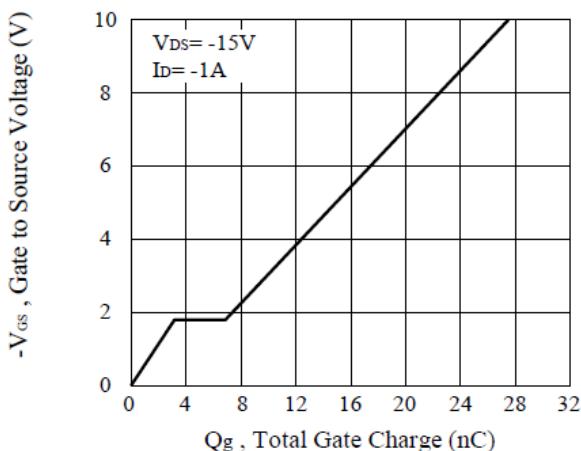


Figure 7. Gate Charge



P-Ch 30V Fast Switching MOSFETs

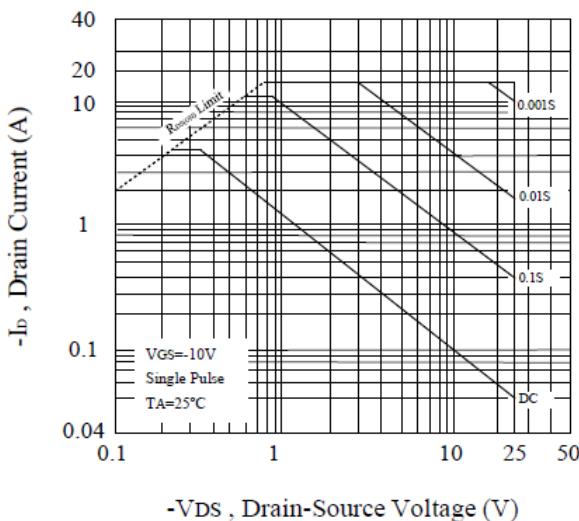


Figure 9. Maximum Safe Operating Area

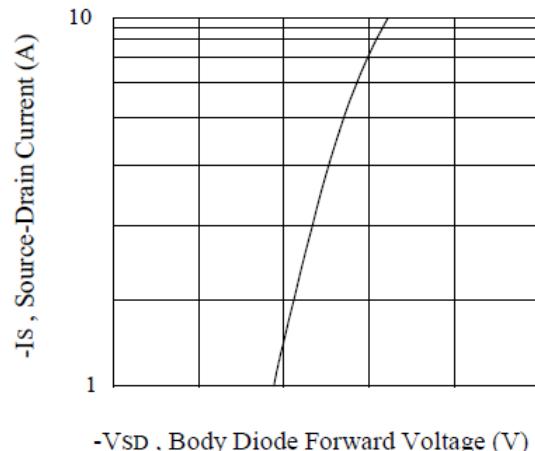


Figure 8. Body Diode Forward Voltage Variation with Source Current

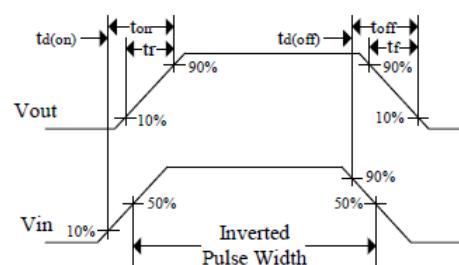
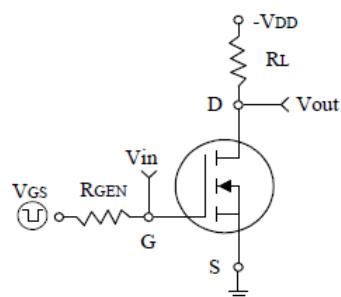


Figure 10. Switching Test Circuit and Switching Waveforms

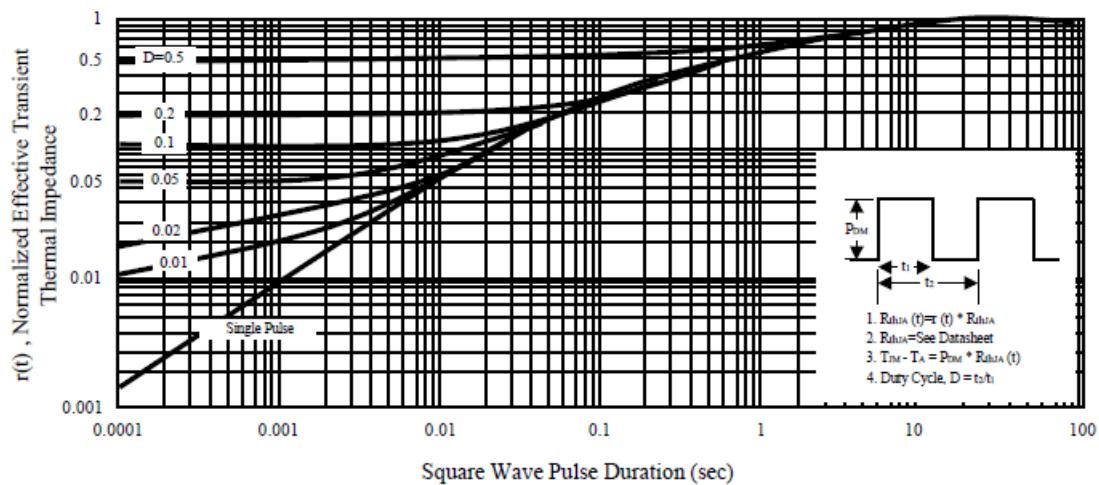


Figure 11. Normalized Thermal Transient Impedance Curve

## Ordering Information

Part Number	Package code	Packaging
HSS06P03	SOT-23L	3000/Tape&Reel

